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Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria,
VA 22313-1450.

PATENT
Attorney Docket No.: 018865-
012810US

on January 26, 2007

TOWNSEND and TOWNSEND and CREW LLP

By 
Andrea S. Beck

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Romel N. Manatad, et al.

Application No.: 10/772,064

Filed: February 3, 2004

For: Alternative Flip Chip in Leaded
Molded Package Design and Method
for Manufacture

Customer No.: 020350

Confirmation No.: 4533

Examiner: William M. Brewster

Art Unit: 2823

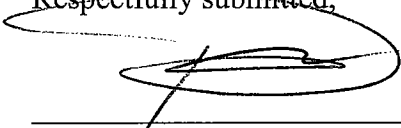
LETTER TO OFFICIAL DRAFTSPERSON

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Notice of Allowance dated December 21, 2006, applicants hereby
submit 4 sheets of formal drawings to be made of record in the above-identified case.

Respectfully submitted,


Patrick R. Jewik
Reg. No. 40,456

TOWNSEND and TOWNSEND and CREW LLP
Two Embarcadero Center, 8th Floor
San Francisco, CA 94111
(415) 576-0200
Fax (415) 576-0300
PRJ:asb
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